

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Assaf Natanzon</td> <td>04/30/2012</td> </tr> <tr> <td>Jehuda Shemer</td> <td>04/30/2012</td> </tr> </tbody> </table>		Name	Execution Date	Assaf Natanzon	04/30/2012	Jehuda Shemer	04/30/2012
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Assaf Natanzon	04/30/2012						
Jehuda Shemer	04/30/2012						
RECEIVING PARTY DATA							
Name:	EMC International Company						
Street Address:	2 Church Street						
City:	Hamilton						
State/Country:	BERMUDA						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13077271</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13077271		
Property Type	Number						
Application Number:	13077271						
CORRESPONDENCE DATA							
Fax Number:							
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
Email:	Docketing@emc.com						
Correspondent Name:	EMC Corporation						
Address Line 1:	176 South Street						
Address Line 2:	Joseph D'Angelo						
Address Line 4:	HOPKINTON, MASSACHUSETTS 01748						
ATTORNEY DOCKET NUMBER:	EMC-10-229						
NAME OF SUBMITTER:	Joseph D'Angelo						
Signature:	/Joseph D'Angelo/						
Date:	05/24/2013						
Total Attachments: 4 source=EMC-10-229_Assignment-Natanzon & Shemer#page1.tif source=EMC-10-229_Assignment-Natanzon & Shemer#page2.tif source=EMC-10-229_Assignment-Natanzon & Shemer#page3.tif source=EMC-10-229_Assignment-Natanzon & Shemer#page4.tif							

CH \$40.00 13077271

ASSIGNMENT

WHEREAS, we, Assaf Natanzon and Jehuda Shemer, have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled *JOURNAL BASED REPLICATION WITH ENHANCE FAILOVER* (Application), the specification of which:

- is being executed on even date herewith and is about to be filed in the United States Patent Office;
- was filed on March 31, 2011 as U.S. Application No. 13/077,271;
- was patented under U.S. Patent No. \_\_\_\_\_ on \_\_\_\_\_.

WHEREAS, EMC International Company (hereinafter "ASSIGNEE"), an unlimited private company organized under the laws of Ireland, with its principal place of activities at 2 Church Street, Hamilton, Bermuda, desires to acquire an interest therein in accordance with agreements duly entered into among EMC International Company, EMC Israel Development Center Ltd. and us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution,


reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

AND, we hereby authorize our attorneys, EMC Corporation, to insert here in parenthesis ( ) the application number and filing date of said Application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

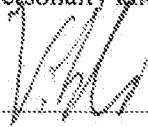
IN TESTIMONY WHEREOF, we have hereunto set our hands and affixed our seals as set forth below:

Date: 30/4/2012

  
Inventor's Signature

Print full name of inventor **Assaf Natanzon**  
Residence **Levanon 95, Tel Aviv, Israel 69395**  
Citizenship **IL**  
Mailing Address **Same as above**

I, Vitali Melamed (name of first witness), whose residential address is  
Hertzal 80, Ramat Gan, Israel  
was personally present and did see Assaf Natanzon (name of person signing the assignment),  
who is personally known to me, execute the above assignment.

  
\_\_\_\_\_ (signature of first witness)  
Signed at Hertzalia, Israel (location of witness signature)  
on this day, 30/4, 2012 (date of signature).

I, Lechod Baruch (name of second witness), whose residential address is  
Mohaliver 1, Hertzalia, Israel  
was personally present and did see Assaf Natanzon (name of person signing the assignment),  
who is personally known to me, execute the above assignment.

Lechod (signature of second witness)  
Signed at Hertzalia, Israel (location of witness signature)  
on this day, 30/4, 2012 (date of signature).

Date: 30/4/2012



.....  
Inventor's Signature

Print full name of inventor

**Jehuda Shemer**

Residence

Brenner 7 Street, Kfar Saba, Israel 44349

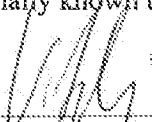
Citizenship

IL

Mailing Address

Same as above

I, Vitali Melamed (name of first witness), whose residential address is  
Hertzel 80, Ramat Gan, Israel  
was personally present and did see Jehuda Shemer (name of person signing the assignment), who  
is personally known to me, execute the above assignment.

 (signature of first witness)

Signed at Hertzelia, Israel (location of witness signature)

on this day, 30/4, 20 12 (date of signature).

I, Lechal Baruch (name of second witness), whose residential address is  
~~Herta~~ Hahadiver 6 Hertzela, Israel  
was personally present and did see Jehuda Shemer (name of person signing the assignment), who  
is personally known to me, execute the above assignment.

Lechal (signature of second witness)

Signed at Hertzelia, Israel (location of witness signature)

on this day, 30/4, 20 12 (date of signature).